SCLS149C - DECEMBER 1982 - REVISED DECEMBER 2002

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-µA Max I_{CC}
- Typical t_{pd} = 8 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Lock Bus-Latch Capability
- True Logic

description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

The 'HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and OEBA) inputs.

OEAB and \overline{OEBA} disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and \overline{OEBA} . Each output reinforces its input in this transceiver configuration. When both OEAB and \overline{OEBA} are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

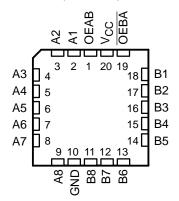
(то	P VIEW)
_		
OEAB [1	[∠] 20 <u>V_{CC}</u>
A1 [2	19 OEBA
A2 [18 🛛 B1
A3 [4	17 🛛 B2
A4 [5	16 🛛 B3
A5 [6	15 🛛 B4
A6 [7	14 🛛 B5
A7 [8	13 🛛 B6
A8 [9	12 🛛 B7

SN54HC623...J OR W PACKAGE SN74HC623...DW, N, OR NS PACKAGE

SN54HC623 ... FK PACKAGE (TOP VIEW)

11 B8

GND 10



TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N Tube		SN74HC623N	SN74HC623N
4000 12 0500		Tube	SN74HC623DW	110000
–40°C to 85°C	SOIC – DW	Tape and reel	SN74HC623DWR	HC623
	SOP – NS	Tape and reel	SN74HC623NSR	HC623
	CDIP – J	Tube	SNJ54HC623J	SNJ54HC623J
–55°C to 125°C	CFP – W	Tube	SNJ54HC623W	SNJ54HC623W
	LCCC – FK	Tube	SNJ54HC623FK	SNJ54HC623FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

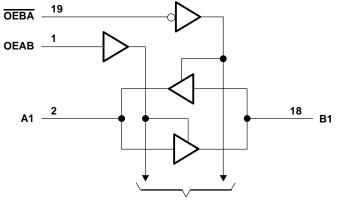
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	FUNCTION TABLE										
INP	UTS										
OEBA	OEAB	OPERATION									
L	L	B data to A bus									
н	Н	A data to B bus									
н	L	Isolation									
L	н	B data to A bus, A data to B bus									

logic diagram (positive logic)



To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (se	e Note 1)	±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CO}	c) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	- 	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ_{JA} (see Note 2):	DW package	58°C/W
	N package	
	NS package	
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

			SN	N54HC62	23	SN	174HC62	23	
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		$V_{CC} = 6 V$	4.2		W	4.2			
		$V_{CC} = 2 V$		1	0.5			0.5	
VIL	Low-level input voltage	$V_{CC} = 4.5 V$		PA I	1.35			1.35	V
		ACC = 6 A		1.8				1.8	
VI	Input voltage		0	20	VCC	0		VCC	V
VO	Output voltage		0)	VCC	0		VCC	V
		$V_{CC} = 2 V$	Q		1000			1000	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 4.5 V$			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature	•	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		7507.00			Т	A = 25°C	;	SN54H	C623	SN74H	C623		
PAR	AMETER	TEST CO	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
				2 V	1.9	1.998		1.9		1.9			
			I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4			
∨он		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V	
			I _{OH} =6 mA	4.5 V	3.98	4.3		3.7		3.84			
			I _{OH} = -7.8 mA	6 V	5.48	5.8		5.2	EW.	5.34			
				2 V		0.002	0.1		0.1		0.1		
			l _{OL} = 20 μA	4.5 V		0.001	0.1	4	0.1		0.1		
VOL		$V_{I} = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1	40	0.1		0.1	V	
			$I_{OL} = 6 \text{ mA}$	4.5 V		0.17	0.26	n_Q	0.4		0.33		
	1		I _{OL} = 7.8 mA	6 V		0.15	0.26	04	0.4		0.33		
ų	OEAB or OEBA	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100	Y	±1000		±1000	nA	
loz	A or B	AO = ACC or 0		6 V		±0.01	±0.5		±10		±5	μA	
ICC		$V_{I} = V_{CC} \text{ or } 0,$	I <mark>O</mark> = 0	6 V			8		160		80	μA	
Ci	OEAB OEBA			2 V to 6 V		3	10		10		10	pF	



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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		ТА	_= 25°C	;	SN54H	C623	SN74H	C623		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		29	105		160		130		
^t pd	A or B	B or A	4.5 V		10	21		32		26	ns	
			6 V		8	18		27		22		
			2 V		112	210		315		265		
ten	OEBA	А	4.5 V		27	42		63		53	ns	
-			6 V		20	36		54		45	-	
			2 V		40	150		225		190		
^t dis	OEBA	A	4.5 V		18	30		45		38	ns	
			6 V		16	26	Q	38		32		
			2 V		112	210	C)	315		265		
ten	OEAB	В	4.5 V		27	42	201	63		53	ns	
			6 V		20	36	4	54		45		
			2 V		40	150		225		190		
^t dis	OEAB	В	4.5 V		18	30		45		38	ns	
			6 V		16	26		38		32		
			2 V		20	60		90		75		
tt		A or B	4.5 V		8	12		18		15	ns	
			6 V		6	10		15		13		

switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

	FROM	то		Т	λ = 25°C	;	SN54HC623	SN74HC623					
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT				
			2 V		44	135	200	170					
^t pd	A or B	B or A	4.5 V		14	27	40	34	ns				
			6 V		11	23	34	29					
			2 V		130	270	405	335					
OEBA	OEBA	А	4.5 V		31	54	81	67	ns				
			6 V		23	46	Q 69	56					
t _{en}			2 V		130	270	405	335					
	OEAB	В	4.5 V		31	54	81	67	ns				
			6 V		23	46	69	56					
			2 V		45	210	315	265					
tt	t _t A		A or B	A or B	A or B	A or B	4.5 V		17	42	63	53	ns
			6 V		13	36	53	45					

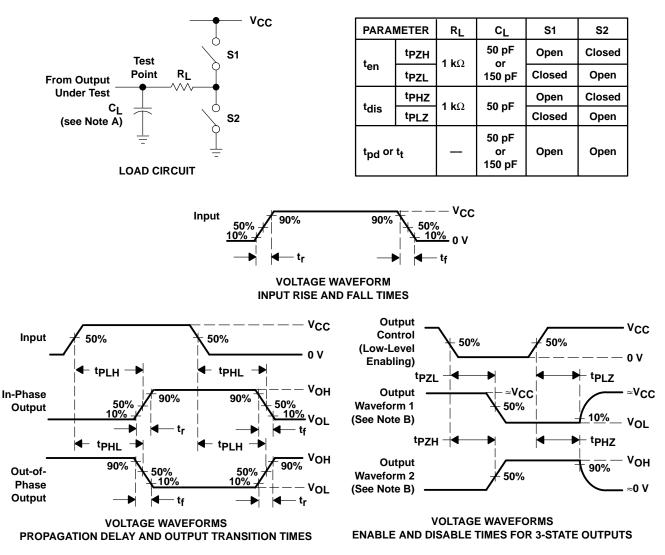
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per transceiver	No load	40	pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. CL includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74HC623DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC623NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC623NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC623NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC623DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74HC623NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1



PACKAGE MATERIALS INFORMATION

5-Aug-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC623DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74HC623NSR	SO	NS	20	2000	346.0	346.0	41.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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